



## High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

VSMY2940RG



VSMY2940G



### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2940 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

### APPLICATIONS

- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors

### FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength:  $\lambda_p = 940$  nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity:  $\phi = \pm 10^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY2940RG	145	$\pm 10$	940	10
VSMY2940G	145	$\pm 10$	940	10

#### Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2940RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2940G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V <sub>R</sub>	5	V
Forward current		I <sub>F</sub>	100	mA
Peak forward current	t <sub>p</sub> /T = 0.5, t <sub>p</sub> = 100 μs	I <sub>FM</sub>	200	mA
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	A
Power dissipation		P <sub>V</sub>	180	mW
Junction temperature		T <sub>j</sub>	100	°C
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C
Soldering temperature	According to Fig. 10, J-STD-020	T <sub>sd</sub>	260	°C
Thermal resistance junction-to-ambient	J-STD-051, soldered on PCB	R <sub>thJA</sub>	250	K/W

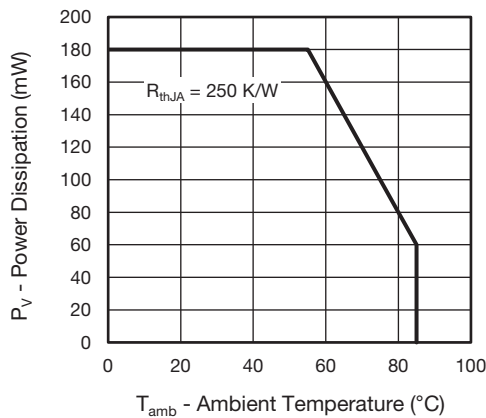


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

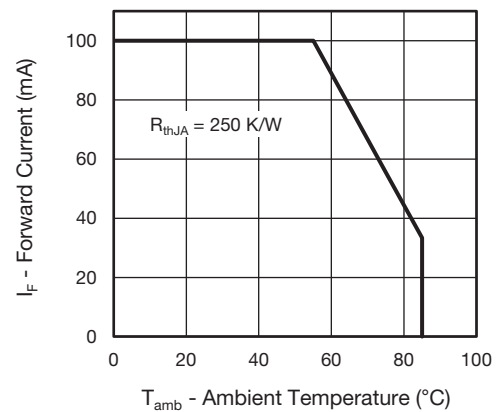


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	-	1.4	1.8	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>	-	2.5	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 100 mA	TK <sub>V<sub>F</sub></sub>	-	-0.7	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation			μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0 mW/cm <sup>2</sup>	C <sub>J</sub>	-	55	-	pF
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	I <sub>e</sub>	75	145	215	mW/sr
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	I <sub>e</sub>	-	1000	-	mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>	-	55	-	mW
Temperature coefficient of radiant power	I <sub>F</sub> = 100 mA	TKφ <sub>e</sub>	-	-0.2	-	%/K
Angle of half intensity		φ	-	± 10	-	deg
Peak wavelength	I <sub>F</sub> = 100 mA	λ <sub>p</sub>	920	940	960	nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ	-	50	-	nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 100 mA	TKλ <sub>p</sub>	-	0.25	-	nm/K
Rise time	I <sub>F</sub> = 100 mA, 10 % to 90 %	t <sub>r</sub>	-	10	-	ns
Fall time	I <sub>F</sub> = 100 mA, 10 % to 90 %	t <sub>f</sub>	-	10	-	ns



**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

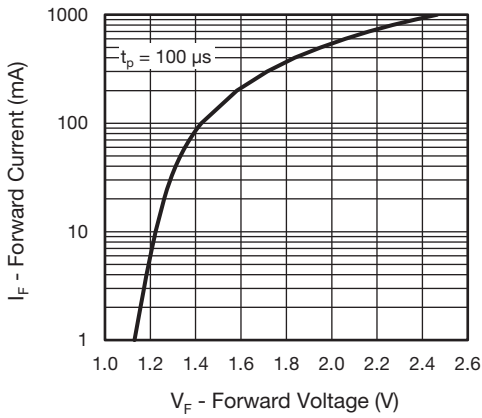


Fig. 3 - Forward Current vs. Forward Voltage

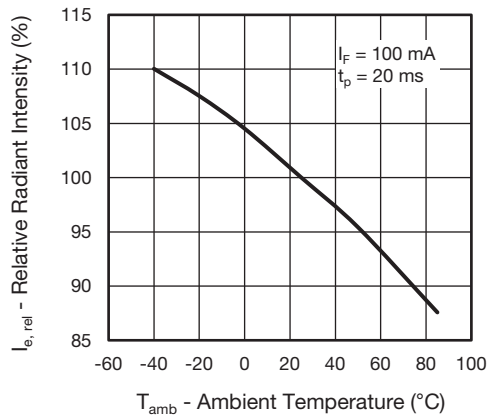


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

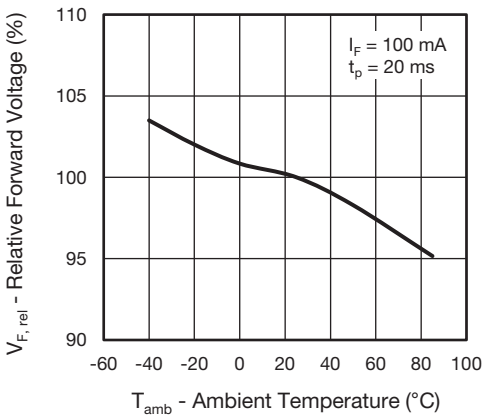


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

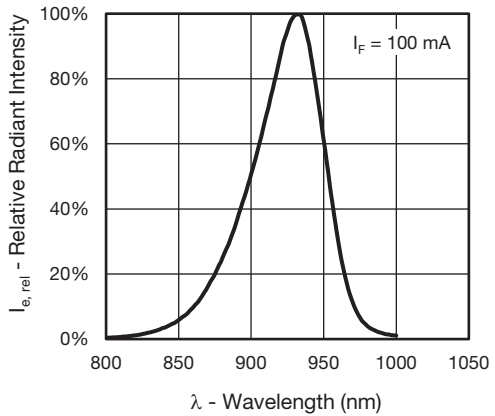


Fig. 7 - Relative Radiant Intensity vs. Wavelength

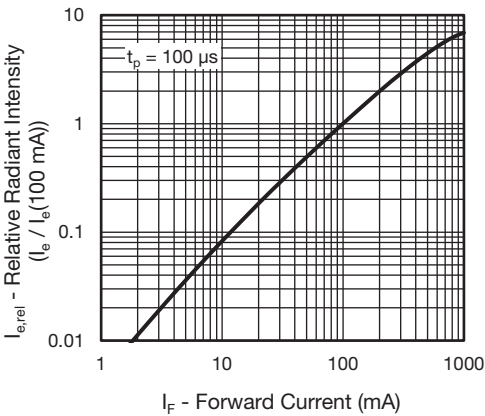


Fig. 5 - Relative Radiant Intensity vs. Forward Current

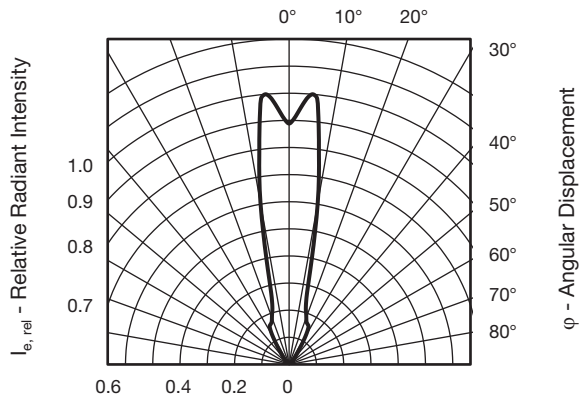
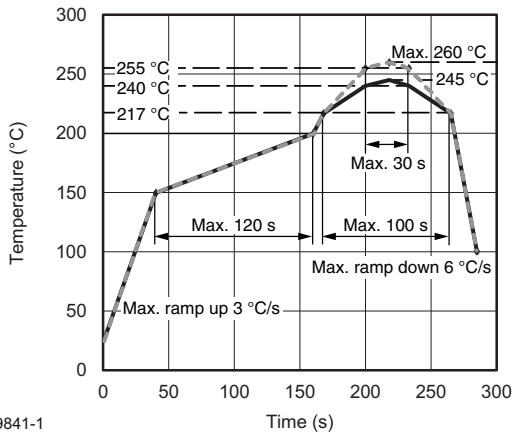


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



## SOLDER PROFILE



19841-1

Fig. 9 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb} < 30\text{ °C}$ ,  $RH < 60\%$

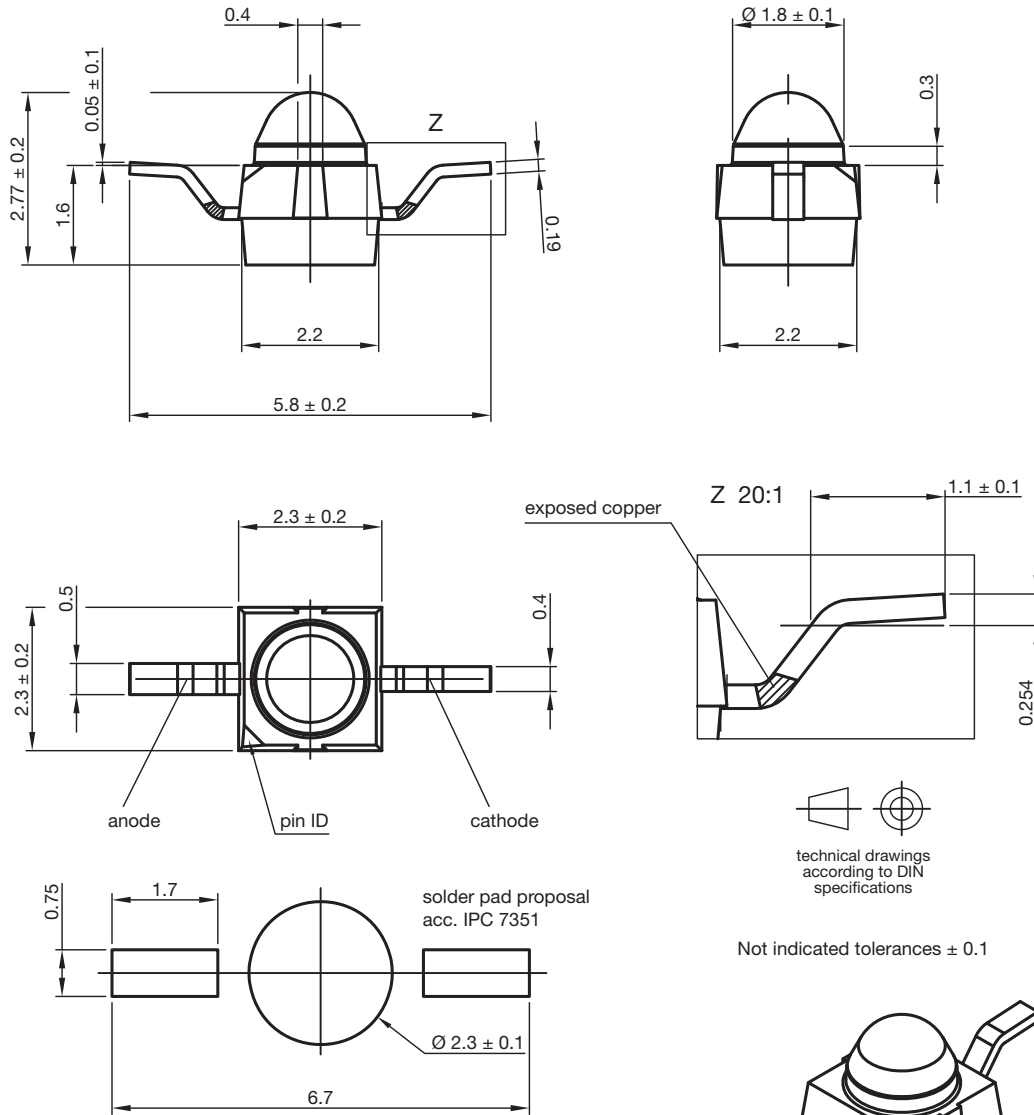
Moisture sensitivity level 2a, according to J-STD-020.

## DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C),  $RH < 5\%$ .



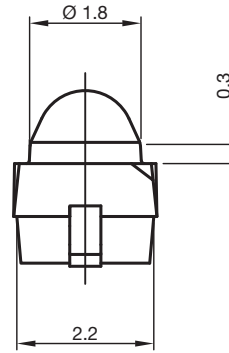
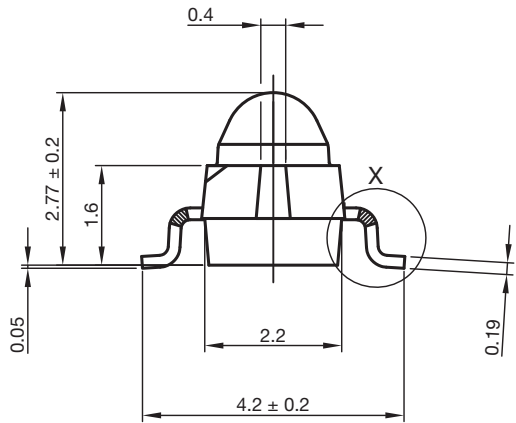
## PACKAGE DIMENSIONS in millimeters: VSMY2940RG



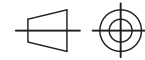
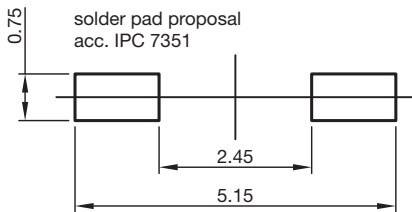
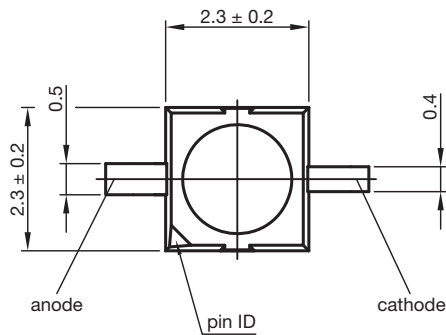
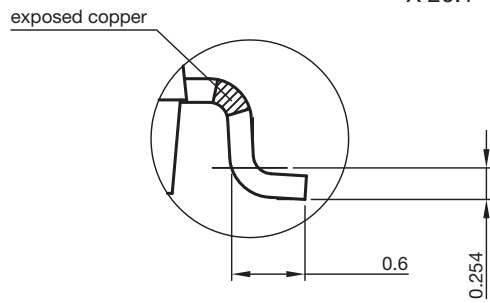
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Issue: 2; 19.09.14



## PACKAGE DIMENSIONS in millimeters: VSMY2940G

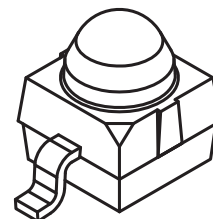


X 20:1



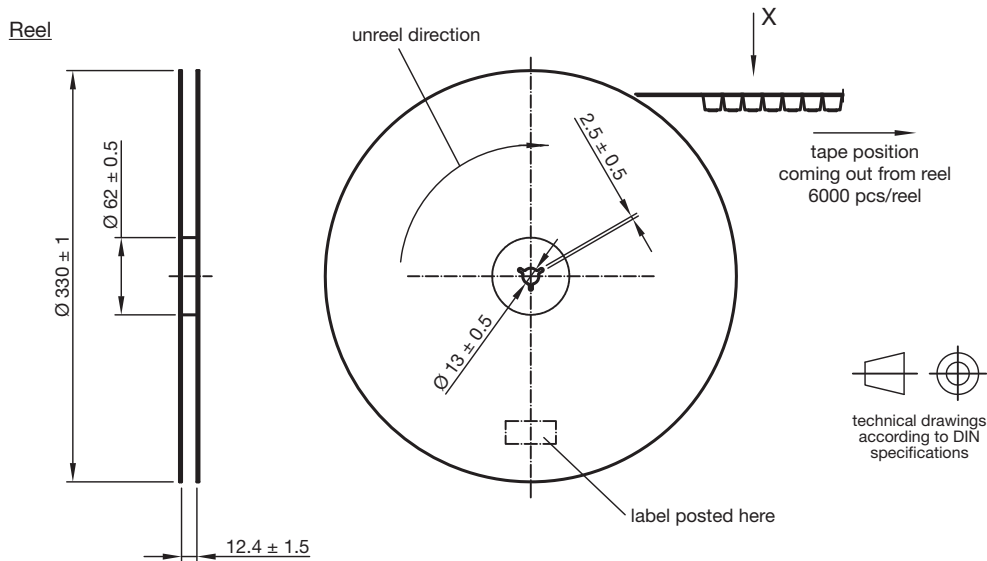
technical drawings according to DIN specifications

Not indicated tolerances ± 0.1

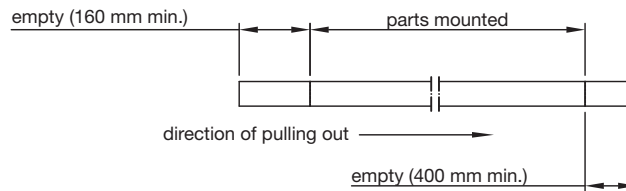


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Issue: 2; 19.09.14

## TAPING AND REEL DIMENSIONS in millimeters: VSMY2940RG

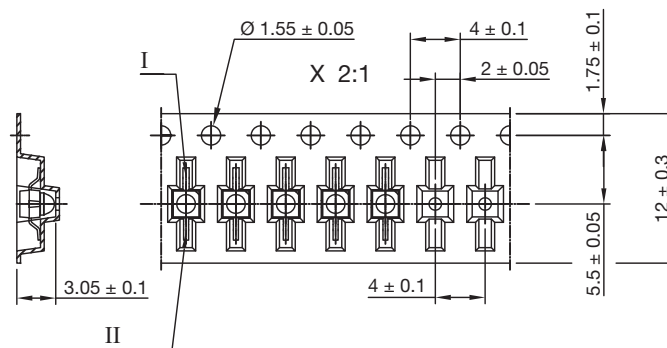


### Leader and trailer tape



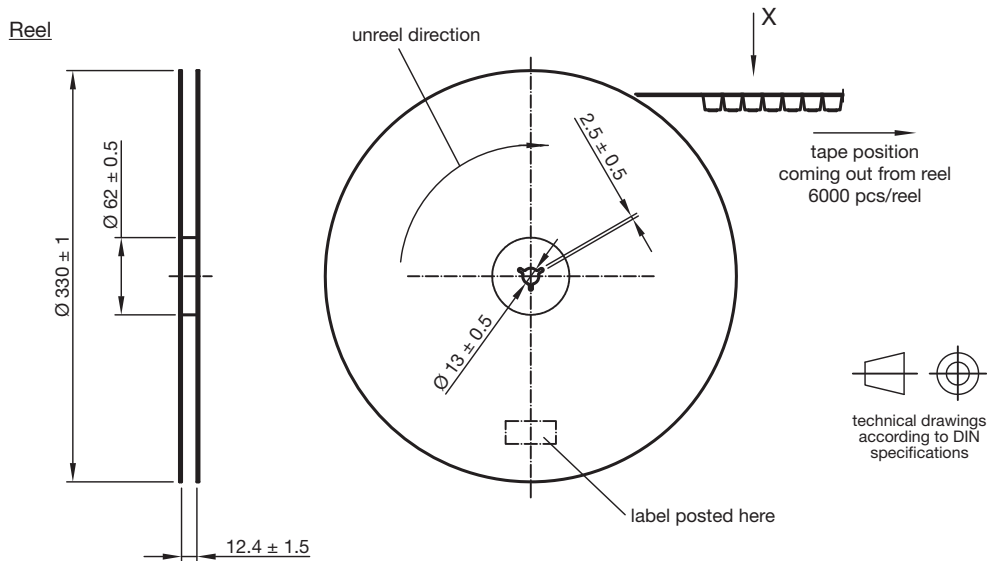
### Terminal position in tape

Device	Lead I	Lead II
VENT2000	Collector	Emitter
VENT2500		
VEMD2000		
VEMD2500	Cathode	Anode
VSMB2000		
VSMG2000		
VSMF2890RG	Anode	Cathode
VSMY2850RG		
VSMY2940RG		

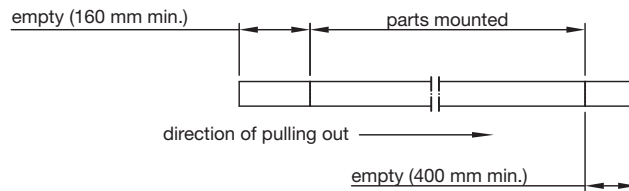


Drawing-No.: 9.800-5100.01-4  
Issue: 4; 19.09.14

## TAPING AND REEL DIMENSIONS in millimeters: VSMY2940G

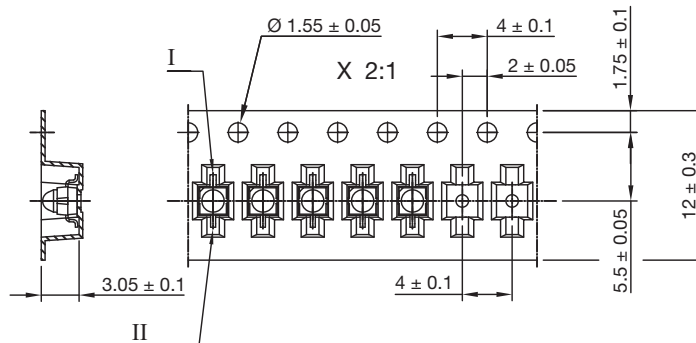


### Leader and trailer tape



### Terminal position in tape

Device	Lead I	Lead II
VSMB2020	Cathode	Anode
VSMG2020		
VEMD2020		
VEMD2520		
VSMF2890G	Collector	Emitter
VEMT2020		
VEMT2520		
VSMY2850G	Anode	Cathode
VSMY2940G		



Drawing-No.: 9.800-5091.01-4  
Issue: 5; 19.09.14





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